

VAC645 / 665

Leading in Vapor Phase Technology

Premium Vacuum Vapor Phase Soldering Machine for Highest Soldering Quality

IBL



Overview

- 2 machine types for different board sizes
- Integrated flexible vacuum system
- Oxygen free soldering
- No overheating of components
- Low power consumption

Standard Equipment / Specification

- Comfortable operation with Touch Screen
- Automatic carrier in- and output
- Program memory up to 50 programs
- Wide variety of adjustable solder profiles
- Low fluid consumption with 2-chamber design and fluid recovery
- Integrated cooling fan for board cooling
- Minimum maintenance and wear due to „cool handling“ (all moving parts outside the process chamber)
- 4 internal channels for comfortable temperature measuring and profiling
- Energy management system
- Fluid level check
- Automatic liquid filtering
- Anti Fog System (AFS) for clear vision of the soldering process (patented)

The Machine

The VAC645 / 665 reflow vapor phase soldering systems (available as batch or inline) are perfect for maximum solder quality and void-free soldering. The combination of the vapor phase soldering with a vacuum process significantly increases the reliability of the finished product. The soldering system operates in a complete inert atmosphere throughout the entire reflow and vacuum process. Many patented features are available and provide a wide range of flexibility.

Special features

- Vacuum process in the vapor phase for void-free soldering (patented)
- Automatic monitoring of vacuum pressure
- IPS, Intelligent Profiling System incl.
 - Soft Vapor Temperature Control (SVTC), temperature regulated profiles
 - Pilot Mode, set-up and profiling in one step
- Lead-free and leaded soldering with one fluid only, with different maximum temperatures
- Built-in software profiling capability
- Syncro-Mode
- Maintenance-free transport system (patented)
- Easy access to process chamber

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Options

- RCS Rapid cooling system (**patented**)
- IR heater system (**patented**)
- VP-Control for convenient documentation and fine adjustment of the process
- Integrated PC-System
- Barcode-system for automatic program-change, traceability and unlimited program storage
- Measurement channels for board temperature recording
- Multi-Level-Mode for easy changeover between different solder heights
- Adapter for double sided PCB boards
- UPS, uninterruptible power supply
- Inline-handling
- Closed-loop-chiller



Technical Data	VAC645	VAC645i	VAC665	VAC665i
Length (Inline)	1355 mm	2040 mm	1355 mm	2040 mm
Depth	2400 mm	3040 mm	2810 mm	3450 mm
Height	1470 mm	1470 mm	1470 mm	1470 mm
Weight	1030 kg	1290 kg	1200 kg	1450 kg
Loading/unloading level		900-1000 mm		900-1000mm
Max. board size (Batch)	635 x 444 x 70 mm	635 x 444 mm	635 x 644 x 70 mm	635 x 644 mm
Max. board size (Inline)		630 x 400 x 55 mm		630 x 400 x 55 mm
Liquid agent filling	40 kg		60 kg	
Water connection	1/2" / 2,5-5 bar, 5,0l/min		1/2" / 2,5-5 bar, 6,0l/min	
Max. heating capacity	10,4 kW		13 kW	
Ø power consumption/h	5,5 kW/h		5,8 kW/h	
Power supply	400/230 VAC, 50Hz, 11kW		400/230 VAC, 50Hz, 16kW	
Main fuse	32A, Typ "gL" or "C"			
External vacuum module	960 x 610 x 1100 mm, 105 kg			

- Technical changes reserved

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